SDLS082

DECEMBER 1983-REVISED MARCH 1988

- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

description

These devices contain dual 4-input positive NOR gates with strobe. They perform the Boolean function:

$$Y = \overline{G(A+B+C+D)}$$
(with 1X and 1 \overline{X} of '23 left open).

The SN5423 and the SN5425 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $^{\circ}\text{C}$. The SN7423 and the SN7425 are characterized for operation from 0 $^{\circ}\text{C}$ to 70 $^{\circ}\text{C}$.

FUNCTION TABLE

	11	NPU1	S		OUTPUT
A	В	С	D	G	Y
Н	×	×	×	н	L
x	Н	×	Х	Н	L
x	×	Н	×	Н	L
x	×	х	Н	Н	L
L	L	L	L	X	н
×	×	х	Х	L	H

Expander inputs are open,
H = high level, L = low level, X = irrelevant

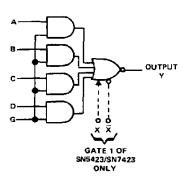
SN5423 . . . J OR W PACKAGE SN7423 . . . N PACKAGE (TOP VIEW)

1X [Īī	U ₁₆	<u>⊃2</u> v [
1A [12	15	_ 1X	
1B []3	14] 2D	
1G []4	13] 2C	
1C [5	12] 2G	
1D []6	11] 2B	
1Y [7	10] 2A	
GND [8	9	2Y	

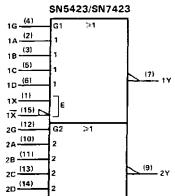
SN5425 . . . J OR W PACKAGE SN7425 . . . N PACKAGE (TOP VIEW)

1A□	U 14∐ Vcc
18 [2	13[] 2D
1G □ 3	12 2C
10 🗖 ₄	11 2G
10 ₫ 5	10 2B
1Ү [[6	9 ∐ 2A
GND 7	8 2Y

logic diagram



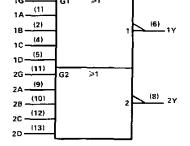
logic symbols†



 † These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers are for J, N, or W packages.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



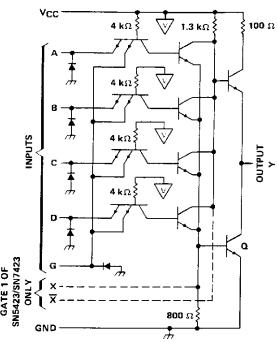


SN5425/SN7425

(3)

SN5423, SN5425, SN7423, SNSN7425 DUAL 4-INPUT NOR GATES WITH STROBE

schematic (each gate)



NOTES: A. Component values shown are nominal.

- B. Both expander inputs are used simultaneously for expanding.
- C. If expander is not used leave X and X open.
- D. A total of four expander gates can be connected to the expander inputs.

₩ - V_{CC} bi

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage VCC (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Interemitter voltage (see Note 2)	
Operating free-air temperature range: SN5423, SN5425 Circuits	55°C to 125°C
SN7423, SN7425 Circuits	0°C to 70°C
Storage temperature range	– 65°C to 150°C

NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.

2. This is the voltage between two emitters of a multiple-emitter transistor.

recommended operating conditions

			'23 , '25			UNIT	
			MIN	NOM	MAX	Olati	
		54 Family	4.5	5	5.5	v	
VCC	Supply voltage	74 Family	4.75	5	5.25	· ·	
VIH	High-level input voltage		2			٧	
VIL	Low-level input voltage				0.8	٧	
Гон	High-level output current				- 0.8	mA	
		54 Family			16	mΑ	
OL	Low-level output current	74 Family			16		
_		54 Familγ	- 55		125	25 °C	
T_A	Operating free-air temperature range	74 Family	0		70		

The '23 is designed for use with up to four '60 expanders.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAF	AMETER		TEST COM	NDITIONS†		MIN	TYP‡	MAX	UNIT	
V _I		V _{CC} = MIN,	I _I = — 12 mA					- 1.5	V	
Vон		V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = - 0.8 mA		2.4	3.4			
VOL		V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA			0.2	0.4	. ٧	
l _l		V _{CC} = MAX,	V1 = 5.5 V					1	mΑ	
	data inputs	VCC = MAX,	V ₁ = 2.4 V					40	μА	
³IH	strobe inputs	ACC - MYV	V - 2.4 V				160	#7		
	data inputs	V _{CC} = MAX,	V. = 0.4 V					1.6	m A	
IIL	strobe inputs	VCC - MAX,	V - 0.4 V	V ₁ = 0.4 V				- 6.4		
		\/ - MAY			54 Family	- 20		- 55		
loss		V _{CC} = MAX			74 Family	– 18		– 55	mΑ	
ССН		V _{CC} = MAX,	All inputs at 0	V	<u> </u>		8	16	mΑ	
TCCL		V _{CC} = MAX,	All inputs at 5	V			10	19	mΑ	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type. Expander inputs X and X are open.

electrical characteristics (SN5423 circuits) using expander inputs, V_{CC} = 4.5 V, T_A = $-55^{\circ}C$

	PARAMETER	TEST	MIN	TYP	MAX	UNIT		
١x̄	Expander current	V _X x = 0.4 V,	I _{OL} = 16 mA				- 3.5	mΑ
V _{BE(Q)}	Base-Emitter voltage of output transistor (Q)	I _{OL} = 16 mA,	$I_X + I_X^{-} = 0.41 \text{ mA},$	$R_{X}\overline{X} = 0$			1.1	٧
VOH	High-level output voltage	$1_{OH} = -0.4 \text{ mA},$	I _X = 0.15 mA,	I ▼ = - 0.15 mA	2.4	3.4		V
VoL	Low-level output voltage	I _{OL} = 16 mA,	$I_X + I_{\overline{X}} = 0.3 \text{ mA},$	$R_{X}\overline{X} = 114 \Omega$		0.2	0.4	V

electrical characteristics (SN7423 circuits) using expander inputs, V_{CC} = 4.75 V, T_A = 0°C

	PARAMETER	TEST	CONDITIONS		MIN	TYP	MAX	UNIT
1 X	Expander current	V _X \overline{\overline{\chi}} = 0.4 \overline{\chi} ,	I _{OL} = 16 mA				- 3.8	mΑ
VBE(Q)	Base-Emitter voltage of output transistor (Q)	I _{OL} = 16 mA,	I _X + I _X = 0.62 mA,	$H_{X}\overline{X} = 0$			1	٧
Voн	High-level output voltage	I _{OH} = - 0.4 mA,	I _X = 0.27 mA,	1 √ = - 0.27 mA	2.4	3.4		V
VOL	Low-level output voltage	IOL= 16 mA,	$1_{X} + 1_{X}^{-} = 0.43 \text{ mA},$	$H_{XX} = 130 \Omega$		0.2	0.4	· V

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$, N = 10, (see note 3)

PARAMETER	TEST CONDITIONS	MIN T	YP MAX	UNIT
tPLH	R_{\perp} = 400 Ω , C_{\perp} = 15 pF		13 22	nş
tPHL	$R_L = 400 \Omega$, $C_L = 15 \rho F$		8 15	ns

NOTE 3: Switching characteristics of the SN5423 and SN7424 are tested with the expander pins open.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25° C.

[§] Not more than one output should be shorted at a time.

PACKAGE OPTION ADDENDUM





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9763601QEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/00403BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/00403BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN5423J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN5423J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN5425J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN5425J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7423N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN7423N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN7425N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7425N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7425N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7425N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7425NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7425NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ5423J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5423J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5423W	OBSOLETE			16		TBD	Call TI	Call TI
SNJ5423W	OBSOLETE			16		TBD	Call TI	Call TI
SNJ5425J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5425J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5425W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5425W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

PACKAGE OPTION ADDENDUM



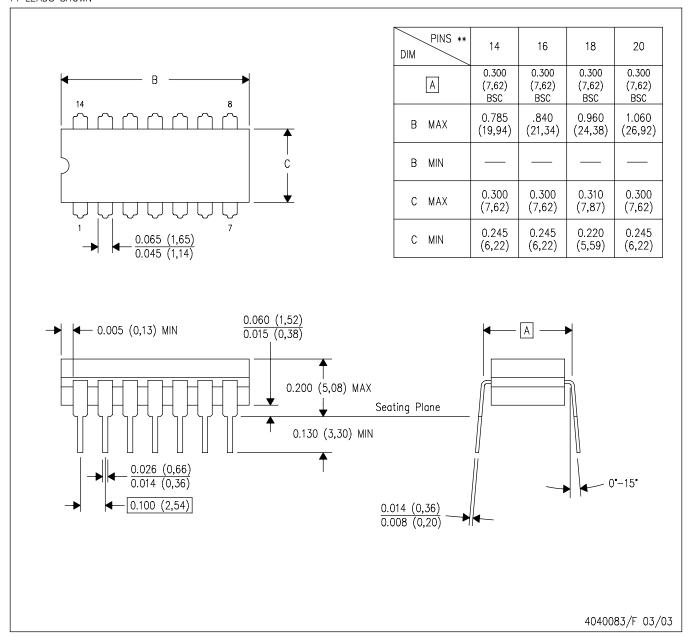
6-Dec-2006

temperature.

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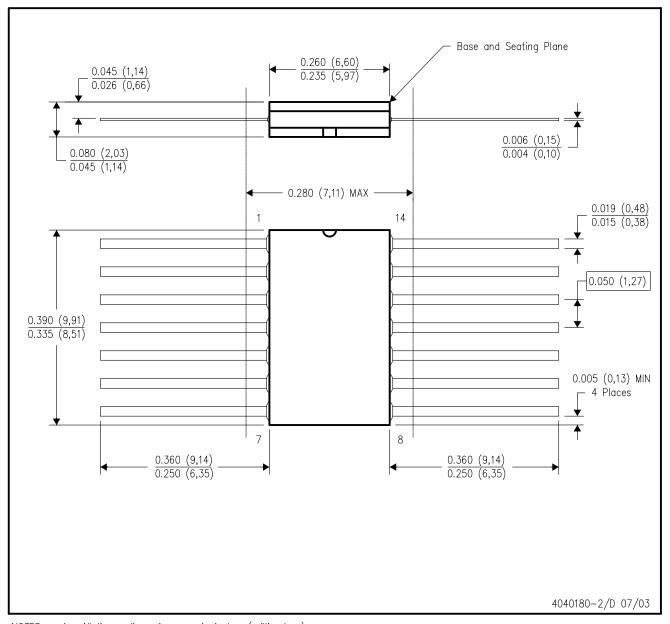
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9763601QEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9763601QE A SNJ5423J
JM38510/00403BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 00403BCA
JM38510/00403BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 00403BCA
JM38510/00403BCA.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 00403BCA
JM38510/00403BCA.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 00403BCA
M38510/00403BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 00403BCA
M38510/00403BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 00403BCA
SN5425J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN5425J
SN5425J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN5425J
SN5425J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN5425J
SN5425J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN5425J
SN7425N	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN7425N
SN7425N	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN7425N
SN7425N.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN7425N
SN7425N.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN7425N
SNJ5423J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9763601QE A SNJ5423J
SNJ5423J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9763601QE A SNJ5423J
SNJ5423J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9763601QE A SNJ5423J

29-May-2025



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Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ5423J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9763601QE A SNJ5423J
SNJ5425J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5425J
SNJ5425J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5425J
SNJ5425J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5425J
SNJ5425J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5425J
SNJ5425W	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5425W
SNJ5425W	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5425W
SNJ5425W.A	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5425W
SNJ5425W.A	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5425W

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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OTHER QUALIFIED VERSIONS OF SN5425, SN7425:

Catalog: SN7425

Military: SN5425

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications





www.ti.com 23-May-2025

TUBE

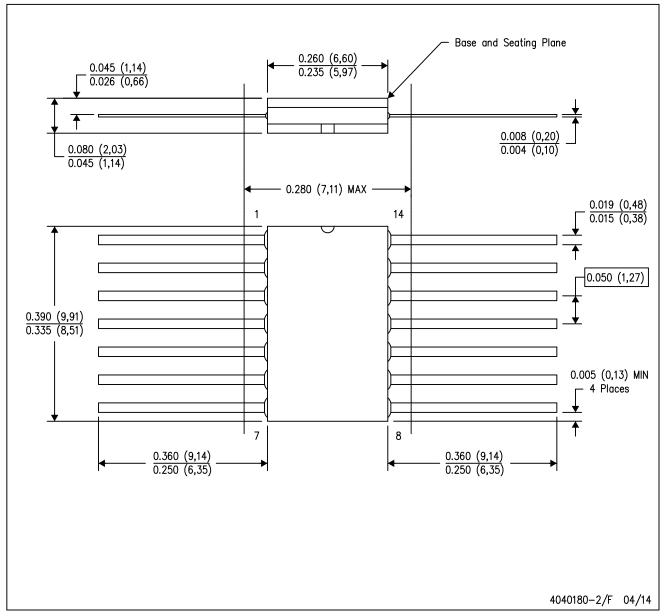


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN7425N	N	PDIP	14	25	506	13.97	11230	4.32
SN7425N	N	PDIP	14	25	506	13.97	11230	4.32
SN7425N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN7425N.A	N	PDIP	14	25	506	13.97	11230	4.32
SNJ5425W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ5425W.A	W	CFP	14	25	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

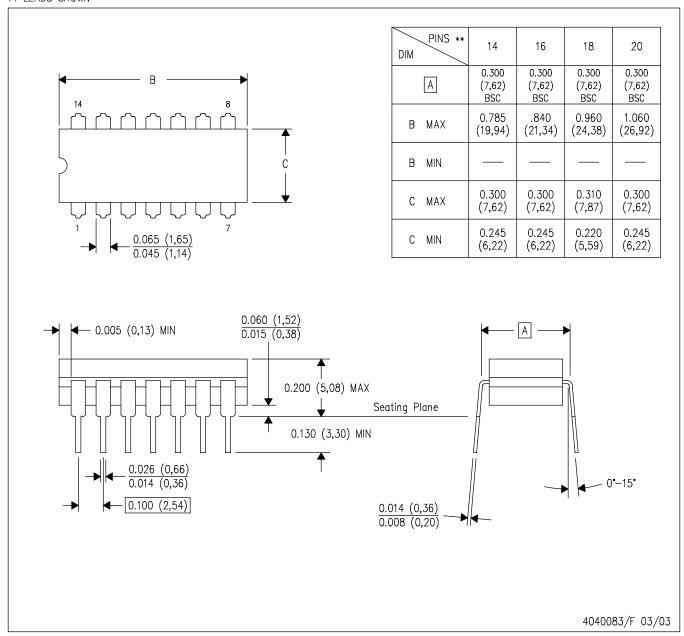


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



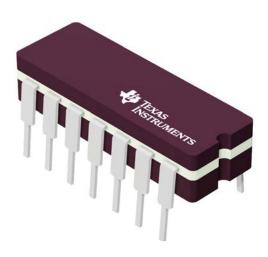
J (R-GDIP-T**)

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





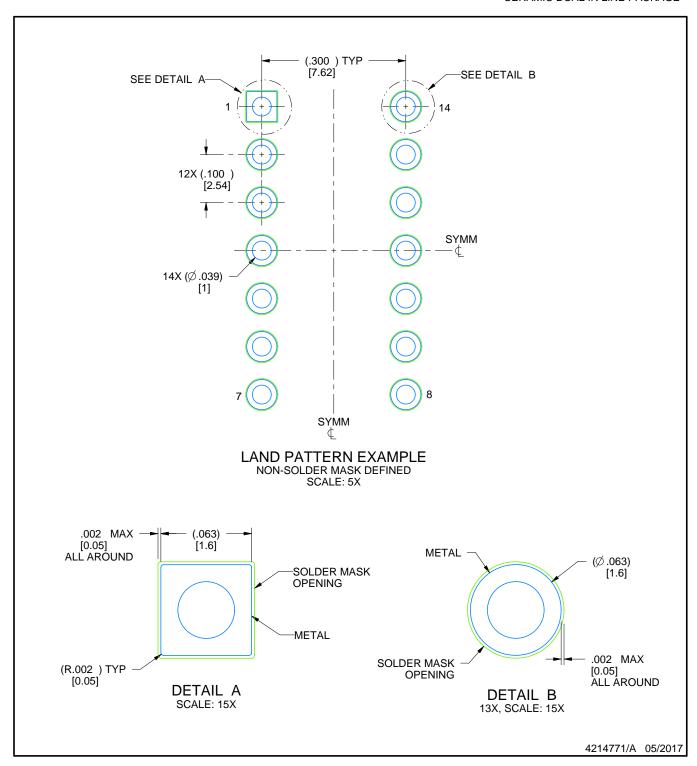
CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE





N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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